

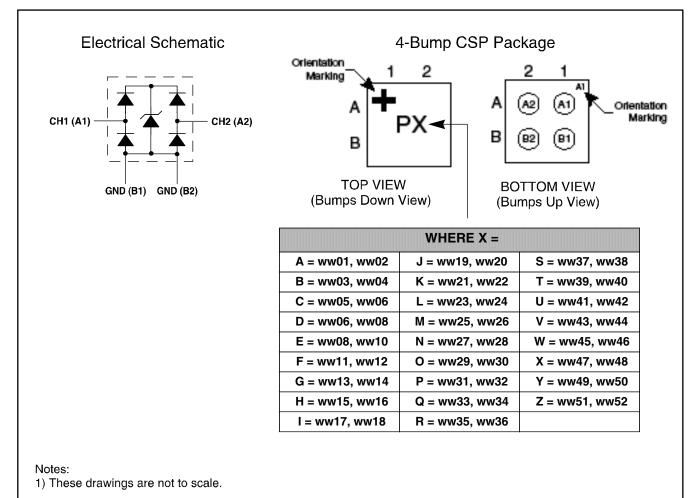


CM6100

Product Description

The 6100 is a 4-bump very low capacitance ESD protection device in 0.4mm CSP form factor. It is fully compliant with IEC 61000-4-2. The CM6100 is RoHS II compliant.

Electrical Schematic / Pin Description



Pin Information

	PIN DESCRIPTIONS					
PIN	IN DESCRIPTION			DESCRIPTION		
A1	ESD Channel 1		B1	Device Ground		
A2	ESD Channel 2		B2	Device Ground		

Ordering Information

PART NUMBERING INFORMATION						
Bumps Package		Variation	Ordering Part Number ¹	Part Marking		
4	CSP	CSP-SAC105	CM6100	Р		

Note 1: Parts are shipped in Tape & Reel form unless otherwise specified.

Electrical Specifications and Conditions

PARAMETERS AND OPERATING CONDITIONS					
PARAMETER	RATING	UNITS			
Storage Temperature Range	-55 to +150	°C			
Operating Temperature Range	-40 to +85	°C			

	ELECTRICAL OPERATING CHARACTERISTICS ^(SEE NOTE 1)					
SYMBOL	PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS
V _{IN}	Input Operating Supply Voltage			3.0	5.5	V
V _B	Breakdown Voltage (Positive)	I _F = 8mA	6			V
I _{LEAK}	Channel Leakage Current	V _{IN} = 3V		±0.1	±0.30	μA
C	Channel Input Capacitance	At 1 MHz, V _{IN} =0V			1.5	pF
ΔC_{IN} Channel Input Capacitance Matching		At 1 MHz, V _{IN} =0V		0.02		pF
V _{esd}	ESD Protection Peak Discharge Voltage at any channel input a) Contact discharge per IEC 61000-4-2 standard b) Air discharge per IEC 61000-4-2 standard	Notes 2	±8 ±15			kV kV
V _{CL}	Channel Clamp Voltage Positive Transients Negative Transients	$I_{pp} = 1A, t_p = 8/20 \mu s$		+9.8 -1.5		V V
R _{dyn}	Dynamic Resistance Positive Transients Negative Transients	$I_{\mu\mu}$ = 1A, t_{μ} = 8/20µS Any I/O pin to Ground		0.7 0.5		Ω Ω

Note 1: All parameters specified at $T_{_A}$ = 25°C unless otherwise noted. Note 2: Standard IEC 61000-4-2 with $C_{_{Discharge}}$ = 150pF, $R_{_{Discharge}}$ = 330 Ω .

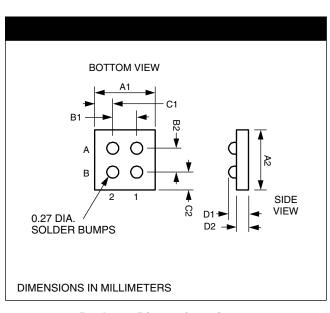
Mechanical Specification

CSP-4 Mechanical Specifications

The CM6100 is supplied in a 4 bump Chip Scale Package (CSP).

PACKAGE DIMENSIONS								
Package		Custom CSP						
Bumps			4					
м	illimete	ers	Inches					
Min	Nom	Max	Min	Nom	Мах			
0.755	0.800	0.845	0.0297	0.0315	0.0333			
0.755	0.800	0.845	0.0297	0.0315	0.0333			
0.395	0.400	0.405	0.0156	0.0157	0.0159			
0.395	0.400	0.405	0.0156	0.0157	0.0159			
0.150	0.200	0.250	0.0059	0.0079	0.0098			
0.150	0.200	0.250	0.0059	0.0079	0.0098			
0.570	0.600	0.630	0.0224	0.0236	0.0248			
0.394	0.406	0.418	0.0155	0.0160	0.0165			
	age hps Min 0.755 0.395 0.395 0.395 0.150 0.150 0.570	age	age Imps Imps Imps Imps <th>age Custom C ps 4 Imps 4 Min Nom Max Min 0.755 0.800 0.845 0.0297 0.755 0.800 0.845 0.0297 0.395 0.400 0.405 0.0156 0.395 0.400 0.405 0.0156 0.150 0.200 0.250 0.0059 0.150 0.200 0.250 0.0059 0.570 0.600 0.630 0.0224</th> <th>age USUSION USUSICUSICUS USUSION USUSION USUSION USUSION USUSION USUSION USUSION U</th>	age Custom C ps 4 Imps 4 Min Nom Max Min 0.755 0.800 0.845 0.0297 0.755 0.800 0.845 0.0297 0.395 0.400 0.405 0.0156 0.395 0.400 0.405 0.0156 0.150 0.200 0.250 0.0059 0.150 0.200 0.250 0.0059 0.570 0.600 0.630 0.0224	age USUSION USUSICUSICUS USUSION USUSION USUSION USUSION USUSION USUSION USUSION U			

Controlling dimension: millimeters



Package Dimensions for CM6100 Chip Scale Package

CM6100

Vertical Structure Specification*

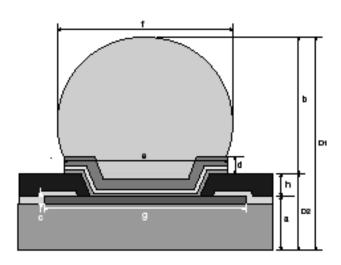


Figure 1. Sectional View

* Daisy Chain CM6000

Ve	Vertical Structure Dimensions (nominal)						
REF.	Parameter	Material	I Dimension				
а	Die Thickness	Silicon	396µm				
h	Repassivation	Polyimide	10µm				
	UBM-(Ti/Cu)	Plated Cu	5.0µm				
d		Sputtered Cu	0.4µm				
		Sputtered Ti	0.1µm				
е	UBM Wetting Area Diameter		240µm				
b	Bump Standoff		194µm				
f	Solder Bump Diameter after Bump Reflow		270µm				
с	Metal Pad Height	AlSiCu	1.5µm				
g	Metal Pad Diameter		310µm				
D2			0.406mm				
D1	Finished Thickness		0.600mm				

Mechanical Specification (cont'd)

CSP Tape and Reel Specifications

PART NUMBER	CHIP SIZE (mm)	POCKET SIZE (mm) B₀ X A₀ X K₀	TAPE WIDTH W	REEL DIA.	QTY PER REEL	P。	P ₁
CM6100	0.8 X 0.8 X 0.60	0.89 x 0.91 x 0.67	8mm	178mm (7")	5000	4mm	4mm

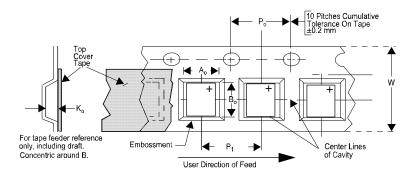


Figure 2. Tape and Reel Mechanical Data

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